APPROVAL SHEET

To：

Customer P/N：

UDE P/N： SS40-ZZ-0011

Description： SFP+ Cage 1X4
Press-fit
With 2 Lightpipe
Packing With Tray

RoHS

Spec No.	Update Date	Revision
SS4020030-00	2020/12/18	A

Approved	Checked	Prepared

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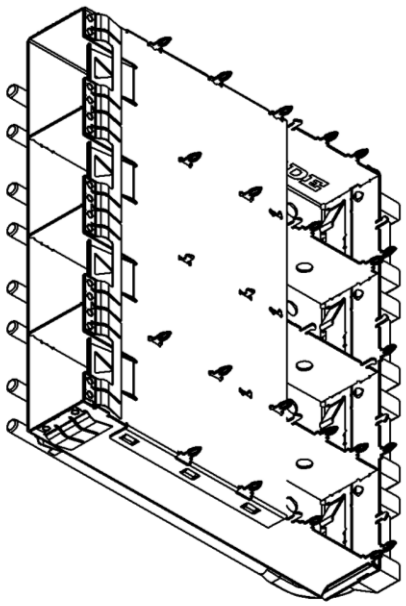
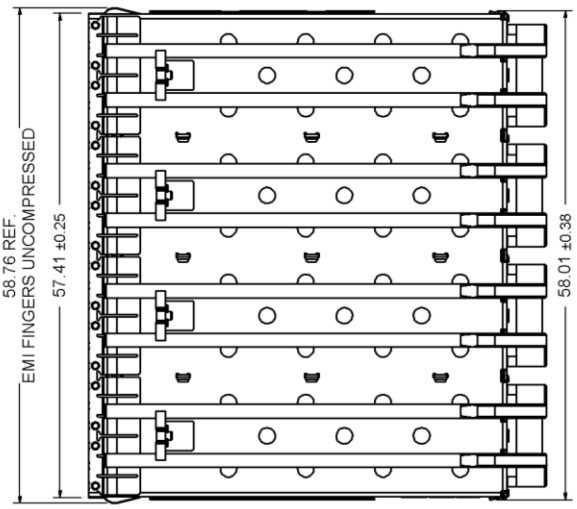
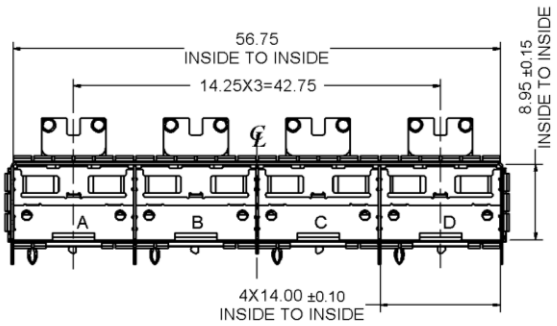
1. MECHANICAL DIMENSION

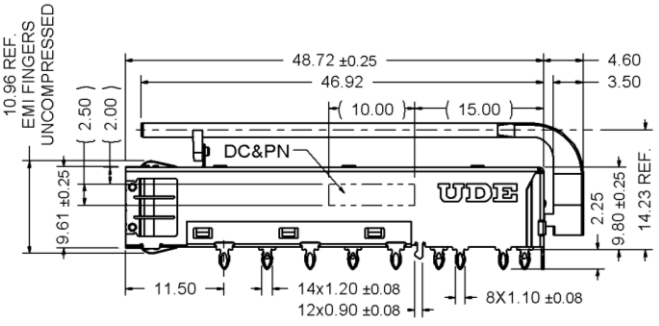
1.1 CAGE assembly Dimension

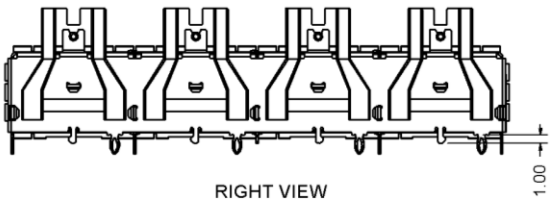
General Tolerance :	X.X : ± 0.38 X.XX : ± 0.20



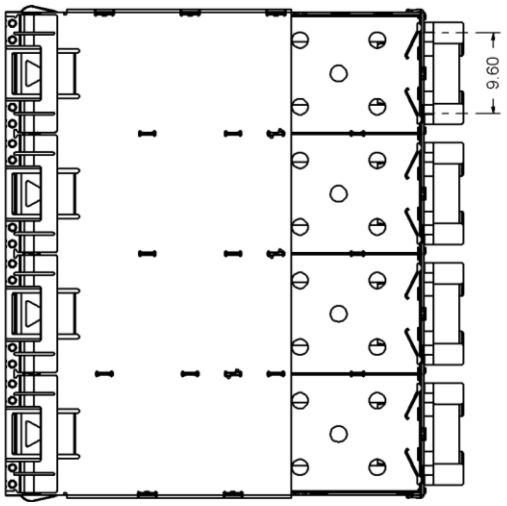








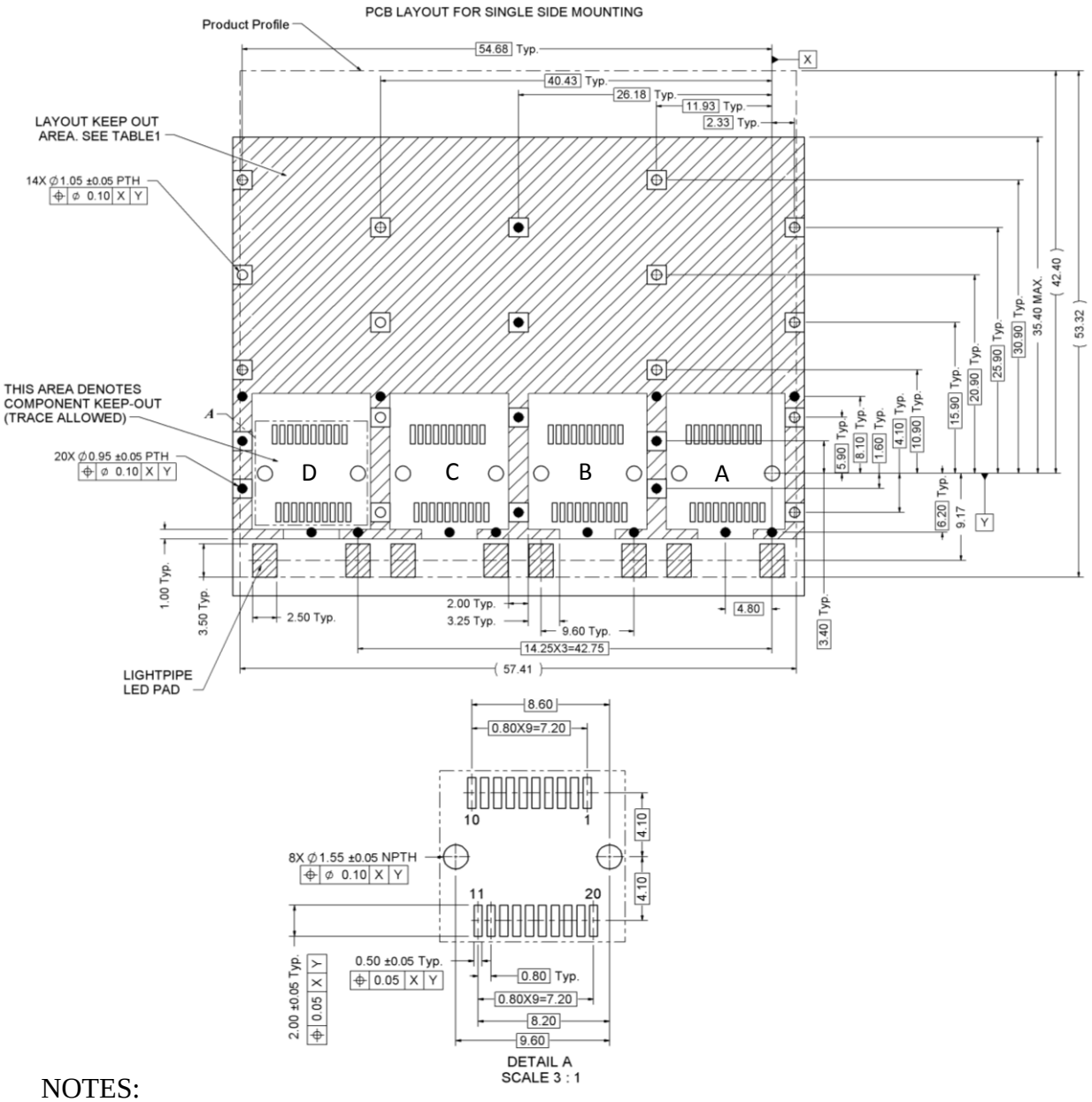
RIGHT VIEW



1.2 Recommended PCB Layout

Component Side of Board

All dimension tolerances are ±0.05mm unless otherwise specified



NOTES:

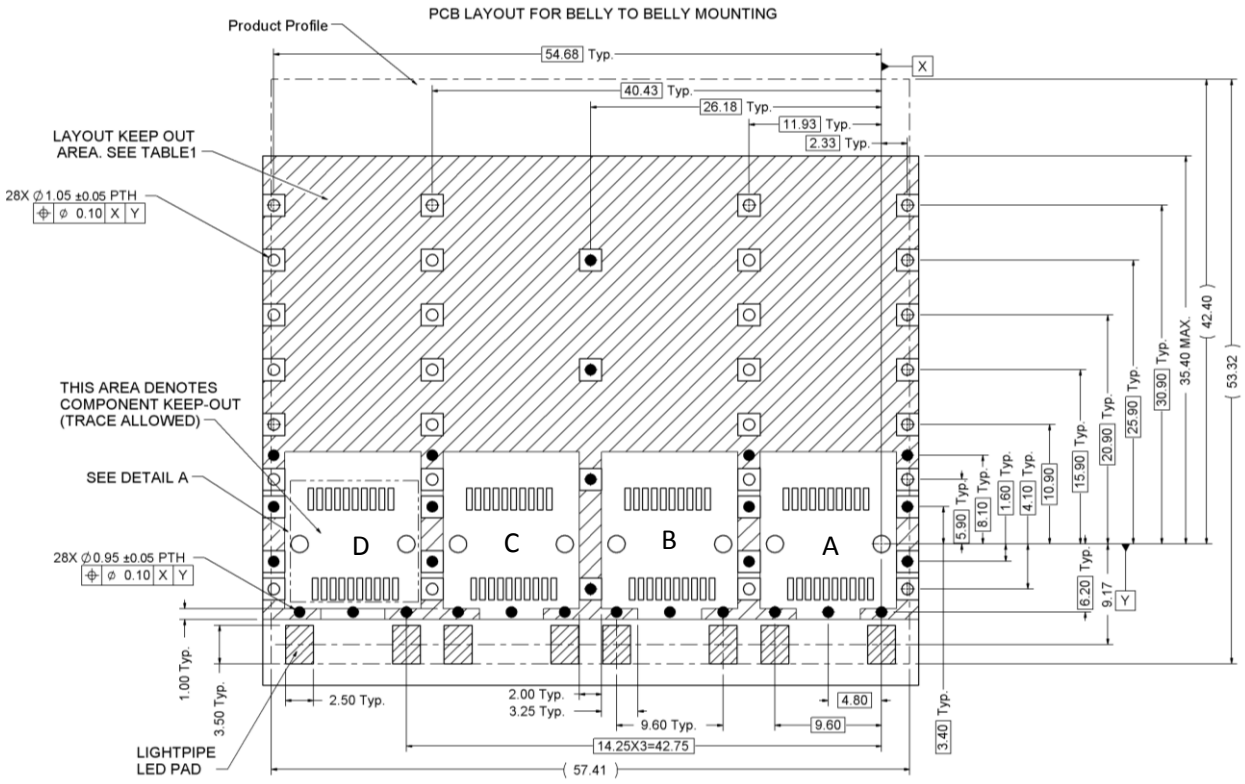
1.PADS AND VIAS CONNECT TO CHASSIS GROUND

RECOMMEND PADS TO BE 2.00mm SQUARE

2.RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

3.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.



NOTES:

1. PADS AND VIAS CONNECT TO CHASSIS GROUND

RECOMMEND PADS TO BE 2.00mm SQUARE

2. RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

3. 3.00mm MINIMUM PCB THICKNESS FOR BELLY TO BELLY SIDED USE.

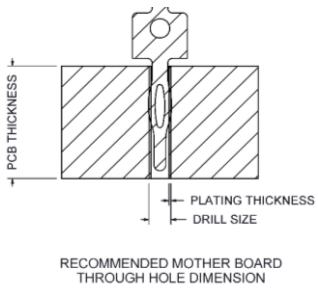
Table1

Layout / Layer	Trace	component	Grounding	Test Point	Via Hole	PTH	NPTH
Component side	X	X	O	X	X	X	O
Inner layer	O	NA	O	NA	O	X	O
Bottom side	O	O	O	O	O	X	O

X--Forbid; O--OK; NA--Not Applicable.

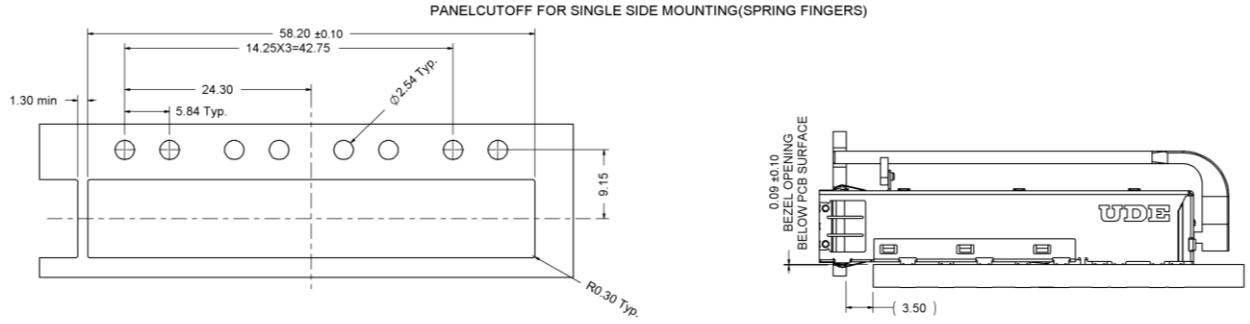
RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

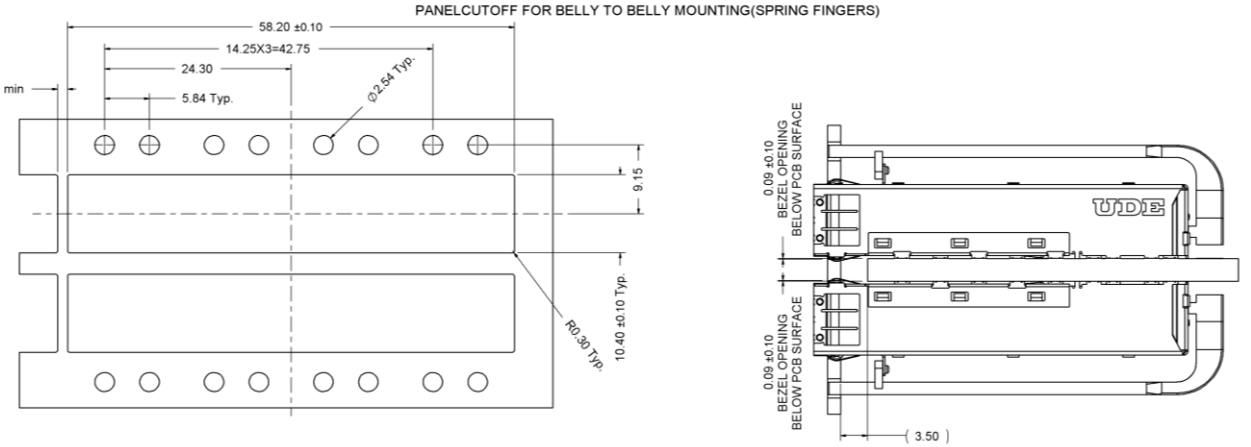
PLATED THROUGH HOLE	1.05 SHIELD PINS	0.95 SHIELD PINS
FINISHED HOLE DIAMETER	1.05±0.05	0.95±0.05
DRILLED HOLE DIAMETER	1.15	1.05
COPPER PLATING	0.025	0.025



RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

1.3 Recommended Panel Cutout





PRESS-FIT ASSEMBLIES
Hand place using proper seating force to engage all Leg tails into plated thru-holes.

Assemblies are to be seated per the instructions associated with the appropriate insertion tool
Note:UDE recommends only one connector assembly be installed at a time.

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
1X4	Copper w/OSP	330±40N

1.4 Packing Information

8 pcs finished goods per tray

6 trays(48 pcs finished goods) per master carton

2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

Top Shell : Copper Alloy, Thickness=0.25mm

Bottom Shell : Copper Alloy, Thickness=0.25mm

Mid Ground : Copper Alloy, Thickness=0.25mm

Inner Spring : SUS304, Thickness=0.20mm

EMI Spring Finger : Ph.Bronze, Thickness=0.08mm

Lightpipe：PC,UL94V-0,Transparent

2.3 Finish

EMI Spring Finger : 30μ" min. Nickel

Top Shell :30μ" min. Nickel

Bottom Shell :30μ" min. Nickel

Mid Ground :30μ" min. Nickel

2.4 Operating and Storage Temperature

Operating Temperature : -40℃ to +85℃

Storage Temperature : -55℃ to +105℃

2.5 SFP CAGE specifications

Insertion force : 18 N max at a max. rate of 25.4mm per minute

(SFP module to SFP cage)

Extraction force : 12.5 N max at a max. rate of 25.4mm per minute

(SFP module to SFP cage)

Cage Retention (Latch strength) : 90N Min.

Durability : 100 cycles for standard class

2.6 Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

2.7 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage,corrosion and deterioration during shipment and storage.

3. Revision History

Issue Date	Revision	Comments	Operator
2020/12/18	A	Initial Release .	Arjun